IN THE CLAIMS

Claim 1 (currently amended): An apparatus for reading a mark on a wafer, comprising:

a support structure ~~having a mark reading side and~~ comprising:

a back support having an upper side, a lower side, a first vertical support side, and a mark reading area, wherein the mark reading area has at least one gradation;

a vertical support having first, second, and third sides, the first side coupled to the first vertical support side of the back support; and

a wafer support ~~side;~~ having a first side coupled to the upper side of the back support and a second side coupled to the second side of the vertical support, the wafer support having first and second major surfaces and at least one slot extending into the wafer support from the first major surface, the at least one slot for receiving said wafer such that a portion of said wafer having the mark extends through the at least one slot;

means for illuminating the mark on said wafer; and

means for reflecting light from said wafer to the at least one gradation of the mark reading area, wherein said means for reflecting light is coupled to the support structure.

Claim 2 (currently amended): The apparatus of claim 1, wherein the back support is a quadrilateral having a rectangular shape, the vertical support is a quadrilateral having a trapezoidal shape, and the wafer support is a quadrilateral having a rectangular shape, wherein the wafer support ~~said mark reading side is vertically oriented and said wafer support side~~ is positioned at an angle ~~and contains at least one slot~~.

Claim 3 (currently amended): The apparatus of claim 2, wherein said at least one slot comprises a plurality of slots, each slot of said plurality of slots ~~is~~ spaced apart from an adjacent slot by at least a width of said wafer.

Claim 4 (original): The apparatus of claim 1, wherein said mark is a scribe mark.

Claim 5 (original): The apparatus of claim 1, wherein said means for illuminating comprises one of a light emitting diode or ambient light.

Claim 6 (currently amended): The apparatus of claim 1, wherein said means for reflecting light comprises a mirror material disposed on a surface of said wafer support ~~side~~.

Claim 7 (original): The apparatus of claim 6, wherein said means for reflecting light comprises a mirror spaced apart from the mirror material.

Claim 8 (original): The apparatus of claim 7, wherein said mirror is a concave mirror.

Claim 9 (currently amended): An apparatus for reading a scribe mark on a wafer, ~~said apparatus having no movable parts~~ comprising:

a structure ~~body having~~ comprising:

first and second plates, said first plate vertically spaced apart from said second plate and said first plate having first and second major surfaces and at least one slot ~~formed therein~~ extending into said first plate from the first major surface, the at least one slot for accepting the wafer, wherein a portion of the wafer having the scribe mark extends through the at least one slot;

a back support having a scribe mark reading area that has at least one gradation; and

a first vertical support coupling a first portion of said first plate to a first portion of said second plate, wherein the first vertical support has a trapezoidal shape, and wherein the structure has no movable parts; and

a reflective material formed on a portion of the second major surface of said first plate, the wherein the reflective material reflects light from the scribe mark to the at least one gradation.

Claim 10 (currently amended): The apparatus of claim 9, further including a second vertical support, wherein said second vertical support couples a second portion of said first plate to a second portion of said second plate.

Claim 11 (original): The apparatus of claim 9, wherein said reflective material is a mirror material.

Claim 12 (original): The apparatus of claim 9, further including a mirror optically coupled to said mirror material.

Claim 13 (original): The apparatus of claim 12, wherein said mirror is a concave mirror.

Claim 14 (original): The apparatus of claim 9, further including a light source for providing light to be reflected to said mirror material.

Claim 15 (original): The apparatus of claim 9, wherein said light source is a diode.

Claim 16 (currently amended): A method for reading a mark on a semiconductor wafer, comprising:

providing a support structure comprising:

a back support having an upper side, a lower side, a first vertical support side, and a mark reading area, wherein the mark reading area has at least one gradation;

a vertical support having first, second, and third sides, the first side coupled to the first vertical support side of the back support; and

a wafer support having a first side coupled to the upper side of the back support and a second side coupled to the second side of the vertical support, the wafer support having first and second major surfaces and at least one slot extending into the wafer support from the first major surface, the at least one slot for receiving said wafer, wherein a portion of said wafer having the mark extends through the at least one slot;

means for reflecting light from said wafer to the at least one gradation of the mark reading area, wherein the means for reflecting light is coupled to the support structure; and

placing ~~providing a~~ the semiconductor wafer having a scribe mark in the at least one slot;

receiving light reflected from the scribe mark; and

reflecting the light reflected from the scribe mark to the ~~a scribe~~ mark reading area.

Claims 17 (original): The method of claim 16, further including providing a source of light, wherein the light illuminates the semiconductor wafer.

Claim 18 (original): The method of claim 16, wherein reflecting the light includes rectifying an image within the light.

Claim 19 (original): The method of claim 16, further including viewing the scribe marks on a plurality of wafers simultaneously.

Claim 20 (original): The method of claim 16, further including using a camera to record images of the scribe marks.